## Martin Springer

List of Publications by Year in descending order

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1307594 1372567 14 115 7 10 citations g-index h-index papers 14 14 14 104 citing authors docs citations times ranked all docs

#	Article	IF	CITATIONS
1	On Residual Stresses and Reference Temperatures in Thermomechanical Simulations of Photovoltaic Modules Using the Finite Element Method. IEEE Journal of Photovoltaics, 2022, 12, 853-859.	2.5	2
2	Environmental influence on cracking and debonding of electrically conductive adhesives. Engineering Fracture Mechanics, 2021, 241, 107398.	4.3	8
3	Employing Weibull Analysis and Weakest Link Theory to Resolve Crystalline Silicon PV Cell Strength Between Bare Cells and Reduced- and Full-Sized Modules. IEEE Journal of Photovoltaics, 2021, 11, 731-741.	2.5	8
4	Representative Modules for Accelerated Thermal Cycling and Static Load Testing., 2021,,.		0
5	Multiscale Modeling of Shingled Cell Photovoltaic Modules for Reliability Assessment of Electrically Conductive Adhesive Cell Interconnects. IEEE Journal of Photovoltaics, 2021, 11, 1040-1047.	2.5	8
6	Failure Analysis of a New Polyamide-Based Fluoropolymer-Free Backsheet After Combined-Accelerated Stress Testing. IEEE Journal of Photovoltaics, 2021, 11, 1197-1205.	2.5	7
7	Viscoelastic Material Characterization and Modeling of Photovoltaic Module Packaging Materials for Direct Finite-Element Method Input. IEEE Journal of Photovoltaics, 2020, 10, 1424-1440.	2.5	18
8	Linear viscoelastic characterization of electrically conductive adhesives used as interconnect in photovoltaic modules. Progress in Photovoltaics: Research and Applications, 2020, 28, 659-681.	8.1	14
9	Environmental Influence on Fracture and Delamination of Electrically Conductive Adhesives., 2020,,.		2
10	A thermo–mechanical cyclic cohesive zone model for variable amplitude loading and mixed–mode behavior. International Journal of Solids and Structures, 2019, 159, 257-271.	2.7	21
11	A thermo-mechanical fatigue damage modeling methodology for power semiconductor robustness validation studies. , 2018, , .		1
12	Fatigue life predictions of metal structures based on a low-cycle, multiaxial fatigue damage model. International Journal of Fatigue, 2018, 116, 355-365.	5.7	25
13	Fatigue crack growth modeling in the metallization of power semiconductors under cyclic thermo-mechanical loading. , $2016,  ,  .$		O
14	Combined simulation of fatigue crack nucleation and propagation based on a damage indicator. Frattura Ed Integrita Strutturale, 2016, 10, 155-161.	0.9	1